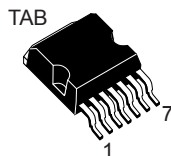
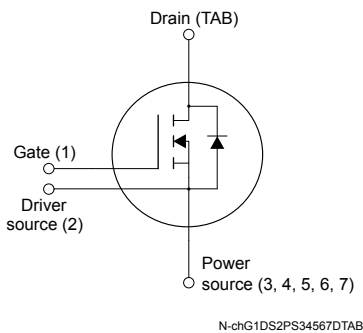


Silicon carbide Power MOSFET 1200 V, 90 A, 21 mΩ (typ., $T_J = 25\text{ °C}$) in an H²PAK-7 package


H²PAK-7

Product status link
[SCTH70N120G2V-7](#)
Product summary

Order code	SCTH70N120G2V-7
Marking	SCT70N12
Package	H ² PAK-7
Packing	Tape and reel

Features

Order code	V_{DS}	$R_{DS(on)}$ typ.	I_D
SCTH70N120G2V-7	1200 V	21 mΩ	90 A

- Very high operating junction temperature capability ($T_J = 175\text{ °C}$)
- Very fast and robust intrinsic body diode
- Extremely low gate charge and input capacitances

Applications

- Charger
- Power supply for renewable energy systems
- High frequency DC-DC converters

Description

This silicon carbide Power MOSFET device has been developed using ST's advanced and innovative 2nd generation SiC MOSFET technology. The device features remarkably low on-resistance per unit area and very good switching performance. The variation of switching loss is almost independent of junction temperature.

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	1200	V
V_{GS}	Gate-source voltage	-10 to 22	V
	Gate-source voltage (recommended operating values)	-5 to 18	
I_D	Drain current (continuous) at $T_C = 25\text{ °C}$	90	A
	Drain current (continuous) at $T_C = 100\text{ °C}$	63	
$I_{DM}^{(1)}$	Drain current (pulsed)	253	A
P_{TOT}	Total power dissipation at $T_C = 25\text{ °C}$	469	W
T_{stg}	Storage temperature range	-55 to 175	°C
T_J	Operating junction temperature range		°C

1. Pulse width is limited by safe operating area.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	0.32	°C/W
$R_{thj-amb}$	Thermal resistance junction-ambient	50	°C/W

2 Electrical characteristics

($T_C = 25\text{ }^\circ\text{C}$ unless otherwise specified).

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}, I_D = 1\text{ mA}$	1200			V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}$			10	μA
		$V_{DS} = 1200\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$		100		
I_{GSS}	Gate-body leakage current	$V_{DS} = 0\text{ V}, V_{GS} = -10\text{ to }+22\text{ V}$		± 10		nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 1\text{ mA}$	1.90	2.45	4.90	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 18\text{ V}, I_D = 50\text{ A}$		21	30	m Ω
		$V_{GS} = 18\text{ V}, I_D = 50\text{ A}, T_J = 175\text{ }^\circ\text{C}$		40		

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 800\text{ V}, f = 1\text{ MHz}, V_{GS} = 0\text{ V}$	-	3540	-	pF
C_{oss}	Output capacitance		-	176	-	pF
C_{rSS}	Reverse transfer capacitance		-	28	-	pF
R_g	Gate input resistance	$f = 1\text{ MHz}, I_D = 0\text{ A}$	-	1	-	Ω
Q_g	Total gate charge	$V_{DD} = 800\text{ V}, I_D = 50\text{ A}, V_{GS} = -5\text{ to }18\text{ V}$	-	150	-	nC
Q_{gs}	Gate-source charge		-	28	-	nC
Q_{gd}	Gate-drain charge		-	63	-	nC

Table 5. Switching energy (inductive load - values based on HiP247 package)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
E_{on}	Turn-on switching energy	$V_{DD} = 800\text{ V}, V_{GS} = -5\text{ to }18\text{ V},$ $I_D = 50\text{ A}, R_G = 3.4\text{ }\Omega$	-	1019	-	μJ
E_{off}	Turn-off switching energy		-	378	-	

Table 6. Switching times (values based on HiP247 package)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 800\text{ V}, I_D = 50\text{ A},$ $R_G = 3.4\text{ }\Omega, V_{GS} = -5\text{ to }18\text{ V}$	-	16	-	ns
t_r	Rise time		-	9.5	-	ns
$t_{d(off)}$	Turn-off delay time		-	37	-	ns
t_f	Fall time		-	22	-	ns

Table 7. Reverse SiC diode characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_{SD}	Forward on voltage	$I_{SD} = 50 \text{ A}$, $V_{GS} = 0 \text{ V}$	-	2.7	-	V
t_{rr}	Reverse recovery time	$I_{SD} = 50 \text{ A}$, $V_{GS} = -5 \text{ to } 18 \text{ V}$, $V_{DD} = 800 \text{ V}$	-	11.16	-	ns
Q_{rr}	Reverse recovery charge		-	276	-	nC
I_{RRM}	Reverse recovery current		-	40	-	A

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area

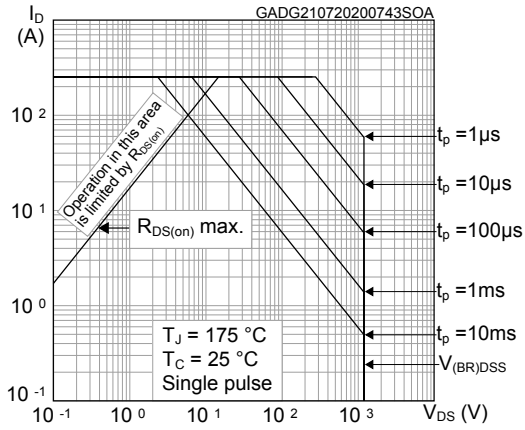


Figure 2. Maximum transient thermal impedance

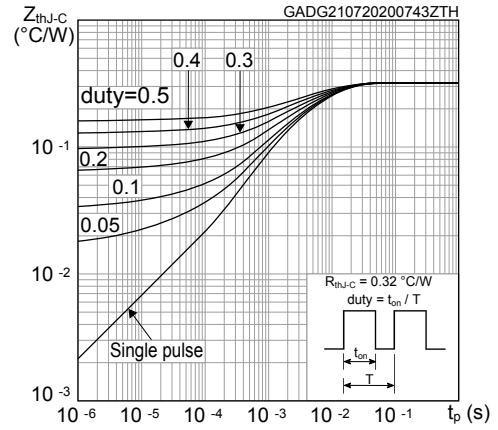


Figure 3. Typical output characteristics ($T_J = 25\text{ }^\circ\text{C}$)

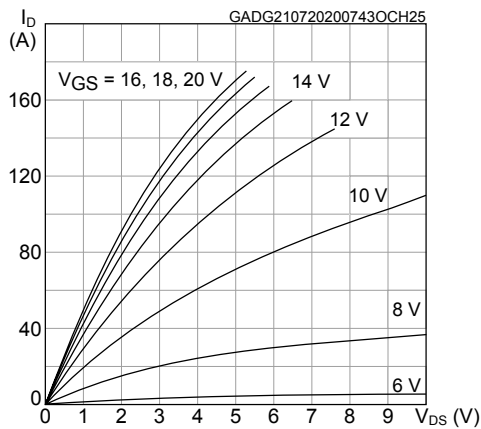


Figure 4. Typical output characteristics ($T_J = 175\text{ }^\circ\text{C}$)

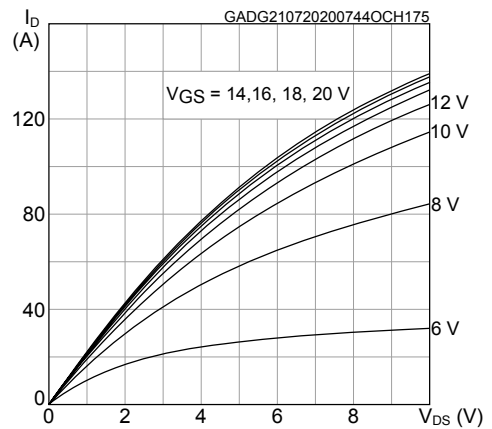


Figure 5. Typical transfer characteristics

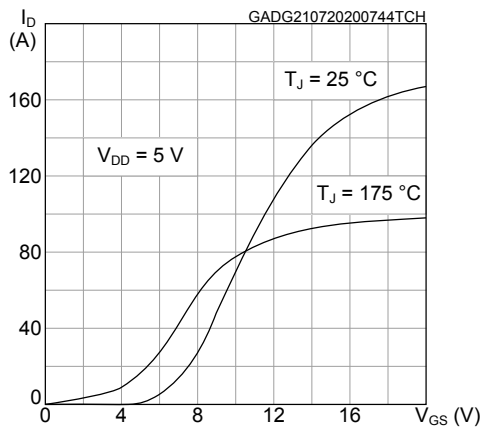


Figure 6. Total power dissipation

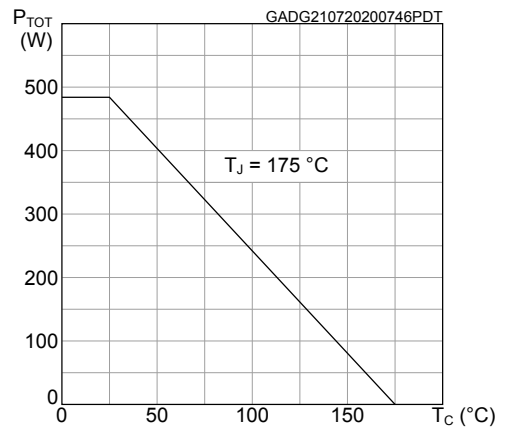


Figure 7. Typical gate charge

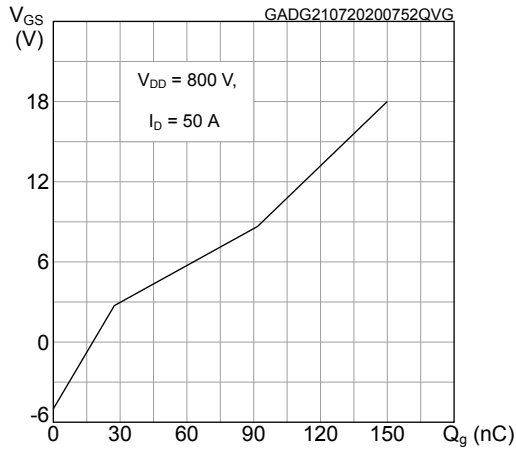


Figure 8. Typical capacitance characteristics

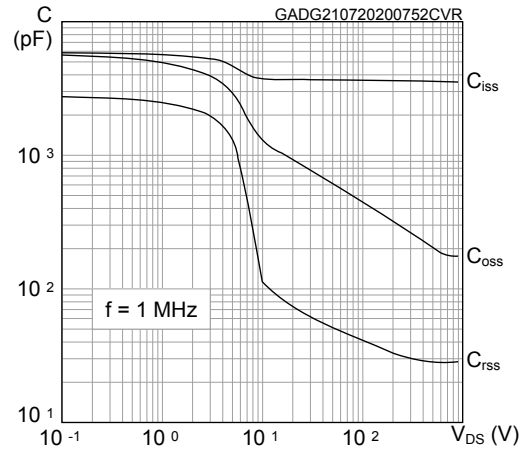


Figure 9. Typical switching energy vs drain current

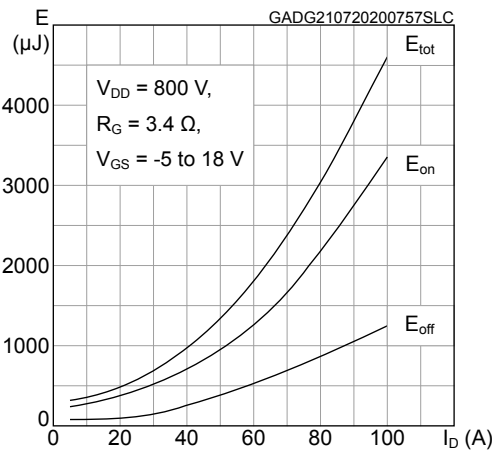


Figure 10. Typical switching energy vs temperature

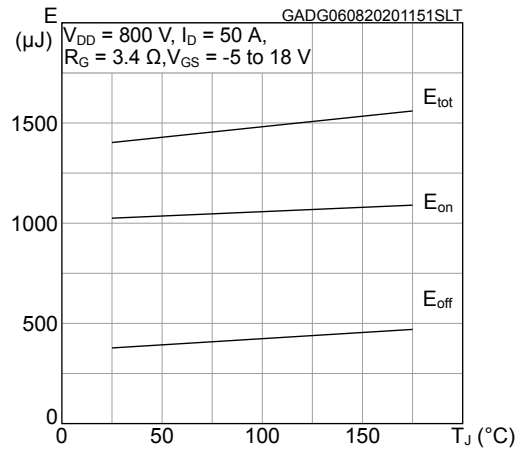


Figure 11. Normalized on-resistance vs temperature

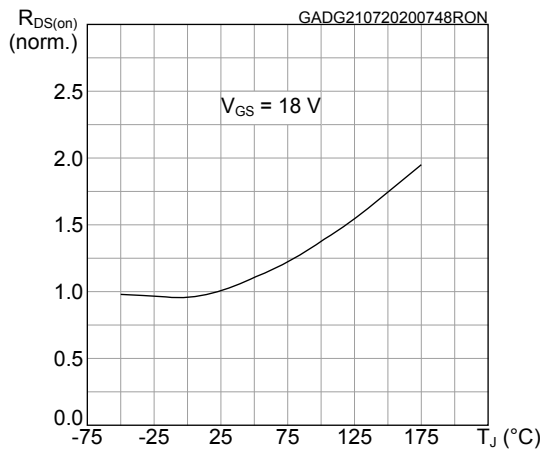


Figure 12. Typical drain-source on-resistance

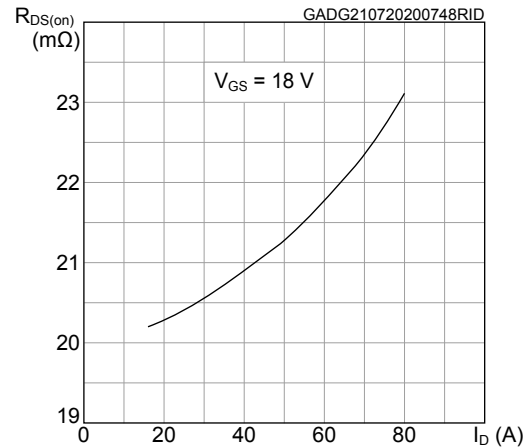


Figure 13. Normalized breakdown voltage vs temperature

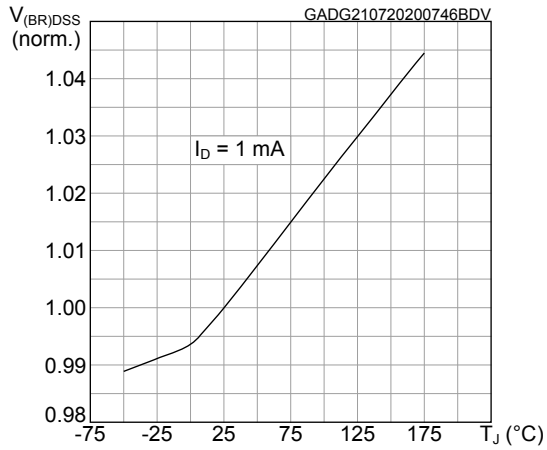


Figure 14. Normalized gate threshold voltage vs temperature

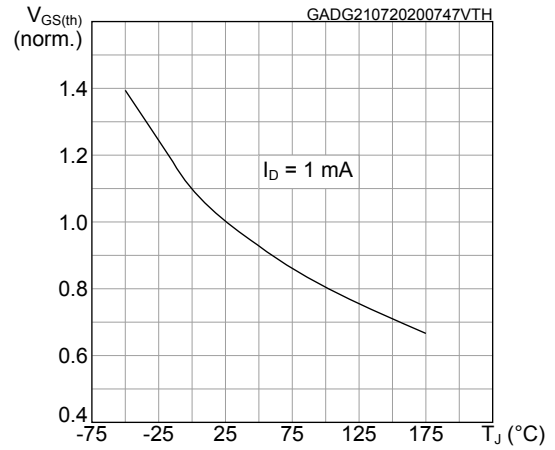


Figure 15. Typical reverse conduction characteristics ($T_J = 25 \text{ °C}$)

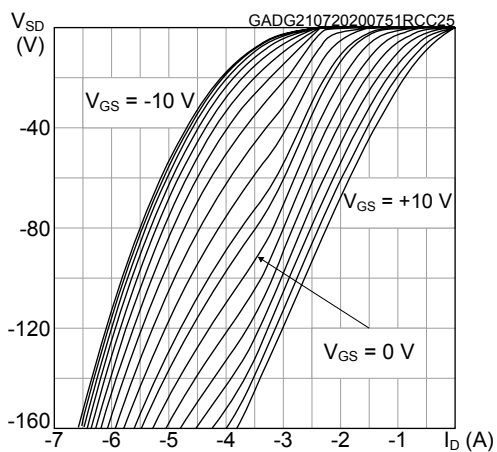


Figure 16. Typical reverse conduction characteristics ($T_J = 200 \text{ °C}$, based on HiP247 package)

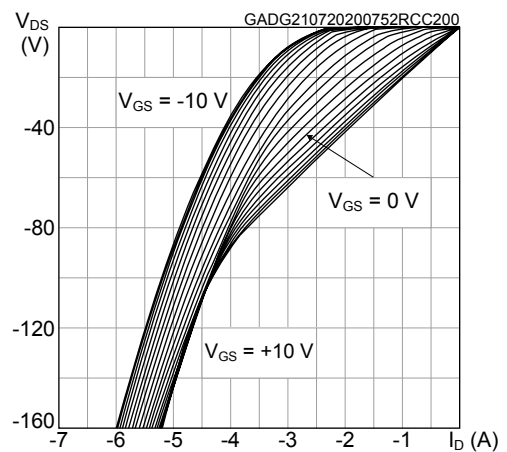
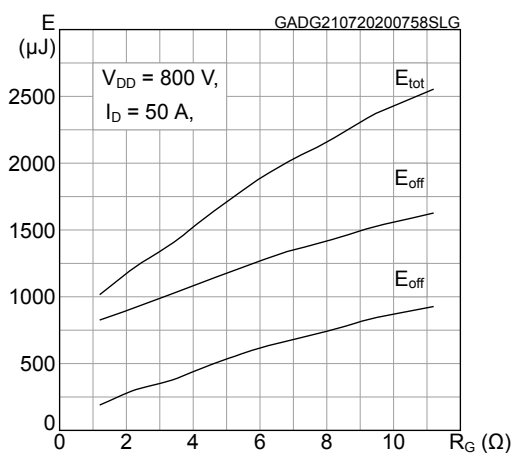


Figure 17. Typical switching energy vs gate resistance



3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.

3.1 H²PAK-7 package information

Figure 18. H²PAK-7 package outline

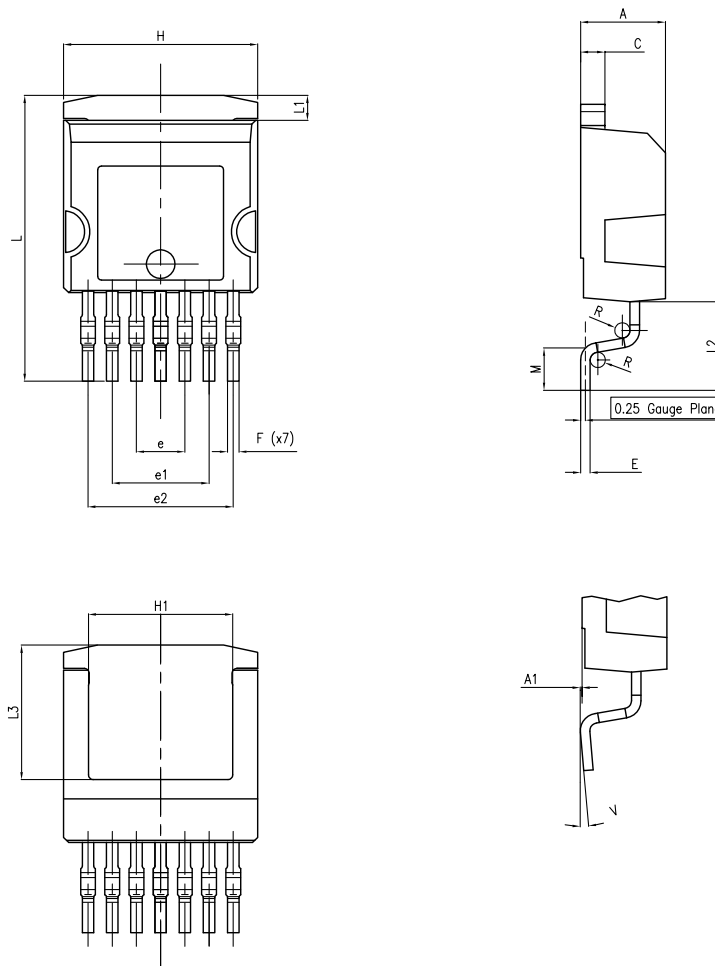
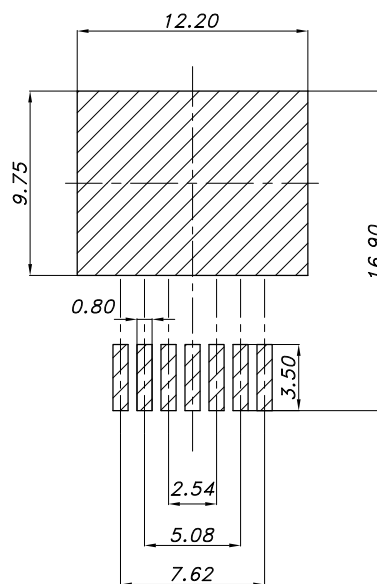


Table 8. H²PAK-7 package mechanical data

Dim.	mm	
	Min.	Max.
A	4.30	4.80
A1	0.03	0.20
C	1.17	1.37
e	2.34	2.74
e1	4.88	5.28
e2	7.42	7.82
E	0.45	0.60
F	0.50	0.70
H	10.00	10.40
H1	7.40	7.60
L	14.75	15.25
L1	1.27	1.40
L2	4.35	4.95
L3	6.85	7.25
M	1.90	2.50
R	0.20	0.60
V	0°	8°

Figure 19. H²PAK-7 recommended footprint

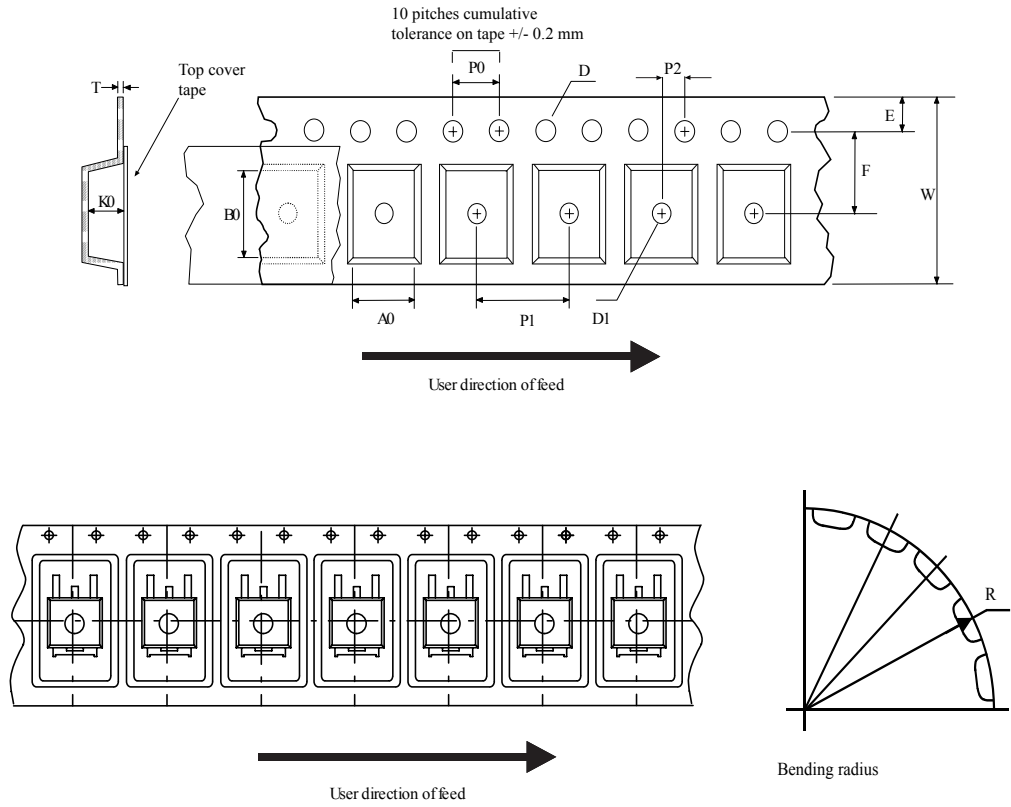


footprint_DM00249216_4

Note: Dimensions are in mm.

3.2 Packing information

Figure 20. Tape outline



AM08852v2

Figure 21. Reel outline

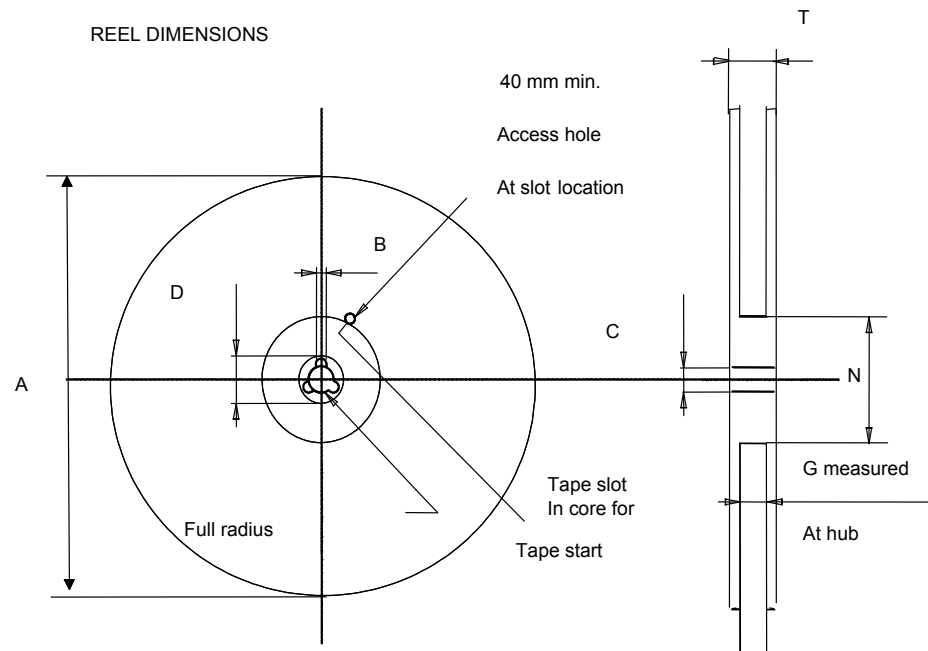


Table 9. Tape and reel mechanical data

Dim.	Tape		Dim.	Reel	
	mm			mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1	Base quantity		1000
P2	1.9	2.1	Bulk quantity		1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

Revision history

Table 10. Document revision history

Date	Revision	Changes
11-Aug-2020	1	First release.

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